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THE WORLDWIDE IC PACKAGING MARKET

2018 EDITION

**The Most Comprehensive Report Available
On The Global IC Packaging Industry**

Report Highlights

- **Industry Overview**
 - ◆ Economic Overview
 - ◆ Semiconductor Industry Analysis

- **Worldwide Semiconductor Device Market Forecasts, 2016–2022**
 - ◆ By Unit Shipments and Revenues
 - ◆ By Packaging Type
 - ◆ By Application
 - ◆ By Major World Region

- **Worldwide IC Packaging Market Forecasts, 2016-2022**
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- **OSAT IC Packaging Market Forecasts, 2016–2022**
 - ◆ IC Packaging Type by Unit Shipments, Revenues and ASP
 - ◆ Competitive Rankings
 - ◆ Company Profiles

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The Worldwide IC Packaging Market, 2018 Edition

Synopsis

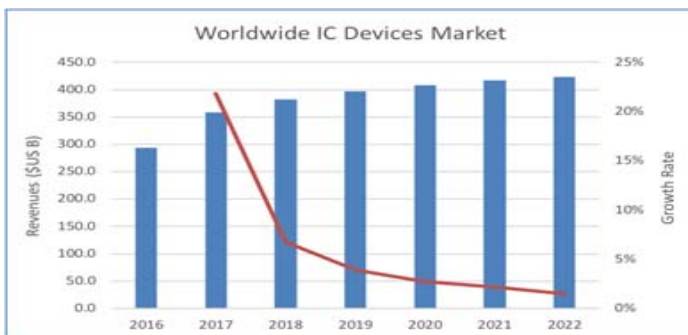
The Worldwide IC Packaging Market, 2018 Edition, a new report from New Venture Research (NVR), examines the global marketplace of integrated circuits (ICs) and the many packaging designs developed for ICs. This comprehensive report presents detailed analysis of a vast and vibrant market that exceeded \$358 billion in 2017. The nearly 500-page report provides insightful analysis of major market trends affecting the semiconductor industry, and presents dozens of tables and figures quantifying both the semiconductor device and IC packaging markets. The report provides extensive and detailed quantitative analysis with forecasts for unit shipments, revenues and package pricing for 31 separate semiconductor device types as well as 14 major packaging categories comprising 44 IC packaging market segments. Virtually every table presents two years of historical data for 2016 and 2017, and five-year forecasts from 2018 through 2022. In addition, numerous graphical figures provide an alternative perspective for understanding the underlying data.

The report is arranged into seven chapters focused on four major topics of discussion. Following an Introductory chapter (Chapter 1) and an Executive Summary (Chapter 2), Chapter 3, "Worldwide Electronics Industry Outlook," examines broad economic trends and the global electronics industry, specifically looking at products that are helping drive the expanding demand for semiconductors and IC packaging technologies. Markets covered includes communications products, computers and peripherals, and consumer products, as well as products for industrial, medical, automotive and commercial aviation and defense sectors.

In Chapter 4, "Semiconductor Device Market Analysis," the report analyzes each semiconductor device type with forecasts provided for unit shipments and revenues presented in terms of function, packaging types, applications and major world regions. Chapter 5, "IC Packaging Market Analysis," examines the IC packaging market in terms of unit shipments, revenues and package pricing for each packaging market segment in terms of semiconductor device type and I/O count. The chapter also provides a short overview of advanced packaging products adapted from NVR's companion report Advanced IC Packaging Technologies, Materials and Markets, 2017 Edition.

Chapter 6, "OSAT Market and Strategy Analysis," focuses on the outsourced semiconductor assembly and test (OSAT) company market segment, vendors who specialize in providing IC packaging and testing services to other companies in the industry. Consisting of more than 100 companies worldwide, the OSAT market segment accounts for a significant and growing sector of the semiconductor market. The report looks not only at the size of the OSAT market, but discusses the various strategies for success shared by the leading competitors. Finally, Chapter 7, "OSAT Company Profiles," presents concise profiles of 40 OSAT companies, providing a cross-section of both large and small competitors. Each profile includes an overview of the company, as well as details of their IC packaging product lines.

The Worldwide IC Packaging Market, 2018 Edition continues NVR's leadership position in analyzing semiconductor device markets and IC packaging products and technologies. This report is an effective and economical tool for any company interested in competing in the semiconductor industry as an aid in assessing the present and future of this dynamic industry. The report sells for \$3995 and is delivered by email as a single-user PDF file. Extra single-user licenses sell for \$500 each and a corporate license is available for an additional \$1500. With the purchase of the report, an Excel spreadsheet containing every table and graphic may be obtained for an additional \$1000 and a printed copy for \$250.



About The Author

Jerry Watkins is an independent senior analyst with more than 20 years of direct experience in the field of market research and consulting. He has worked for leading research companies such as Frost & Sullivan, Lucid Information Services, and NSI Research, both in management and as a writer. Mr. Watkins has authored many syndicated reports, previously in the telecommunications and office automation sectors and more recently in the semiconductor industry, writing on subjects that include IC packaging and merchant embedded computing. He holds two university degrees, including a B.A. in History and an M.A. in International Studies, but he feels that market research best fulfills his lifelong passion for inquiry into difficult subject matter and making it comprehensible to a wide audience. Mr. Watkins has lived and worked in Silicon Valley for most of his career.

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ANST China	Hana Microelectronics	SPiL
ASE	HANA Micron	SPEL Semiconductor
Azimuth	Interconnect Systems	STATS ChipPAC
Carsem	J-Devices	Tera Probe
Chant World Technology	Jiangsu Changjiang Electronics	Tianshui Huatian Tech
China Wafer Level CSP	Lingsen Precision Industries	TongFu Microelectronics
ChipMOS	nepes Corp.	Unisem
Cirtek	OSE	UTAC
CONNECTEC Japan	Palomar Technologies	Walton Advanced Engineering
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